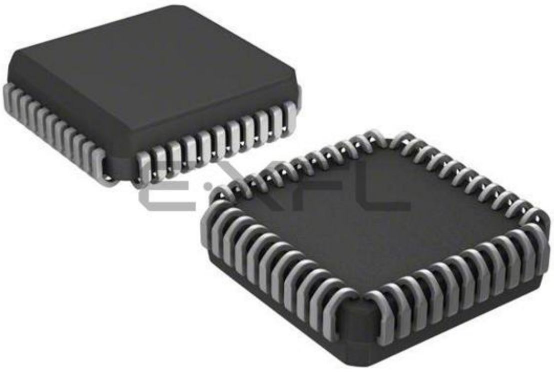
Microchip Technology - PIC16C74A-20I/L Datasheet



Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	7KB (4K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	A/D 8x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c74a-20i-l

Table of Contents

For register and module descriptions in this data sheet, device legends show which devices apply to those sections. As an example, the legend below would mean that the following section applies only to the PIC16C72, PIC16C73A and PIC16C74A devices.

Applicable Devices						
72	73	73A	74	74A	76	77

To Our Valued Customers

We constantly strive to improve the quality of all our products and documentation. We have spent an exceptional amount of time to ensure that these documents are correct. However, we realize that we may have missed a few things. If you find any information that is missing or appears in error, please use the reader response form in the back of this data sheet to inform us. We appreciate your assistance in making this a better document.

TABLE 1-1: PIC16C7XX FAMILY OF DEVCES

		PIC16C710	PIC16C71	PIC16C711	PIC16C715	PIC16C72	PIC16CR72(1)
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20	20
Memory	EPROM Program Memory (x14 words)	512	1K	1K	2K	2K	—
	ROM Program Memory (14K words)	—	—	—	—	—	2K
	Data Memory (bytes)	36	36	68	128	128	128
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0	TMR0	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
	Capture/Compare/ PWM Module(s)	—	—	—	—	1	1
	Serial Port(s) (SPI/I^{2}C, USART)	—	—	—	—	SPI/I^{2}C	SPI/I^{2}C
	Parallel Slave Port	—	—	—	—	—	—
Features	A/D Converter (8-bit) Channels	4	4	4	4	5	5
	Interrupt Sources	4	4	4	4	8	8
	I/O Pins	13	13	13	13	22	22
	Voltage Range (Volts)	3.0-6.0	3.0-6.0	3.0-6.0	3.0-5.5	2.5-6.0	3.0-5.5
	In-Circuit Serial Programming	Yes	Yes	Yes	Yes	Yes	Yes
	Brown-out Reset	Yes	—	Yes	Yes	Yes	Yes
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	28-pin SDIP, SOIC, SSOP	28-pin SDIP, SOIC, SSOP

		PIC16C73A	PIC16C74A	PIC16C76	PIC16C77
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20
Memory	EPROM Program Memory (x14 words)	4K	4K	8K	8K
	Data Memory (bytes)	192	192	368	368
Peripherals	Timer Module(s)	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
	Capture/Compare/PWM Module(s)	2	2	2	2
	Serial Port(s) (SPI/I^{2}C, USART)	SPI/I^{2}C, USART	SPI/I^{2}C, USART	SPI/I^{2}C, USART	SPI/I^{2}C, USART
	Parallel Slave Port	—	Yes	—	Yes
	A/D Converter (8-bit) Channels	5	8	5	8
Features	Interrupt Sources	11	12	11	12
	I/O Pins	22	33	22	33
	Voltage Range (Volts)	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0
	In-Circuit Serial Programming	Yes	Yes	Yes	Yes
	Brown-out Reset	Yes	Yes	Yes	Yes
	Packages	28-pin SDIP, SOIC	40-pin DIP; 44-pin PLCC, MQFP, TQFP	28-pin SDIP, SOIC	40-pin DIP; 44-pin PLCC, MQFP, TQFP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C7XX Family devices use serial programming with clock pin RB6 and data pin RB7.

Note 1: Please contact your local Microchip sales office for availability of these devices.

NOTES:

FIGURE 10-1: CCP1CON REGISTER (ADDRESS 17h)/CCP2CON REGISTER (ADDRESS 1Dh)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	CCPxX	CCPxY	CCPxM3	CCPxM2	CCPxM1	CCPxM0
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
- n =Value at POR reset

bit 7-6: **Unimplemented:** Read as '0'

bit 5-4: **CCPxX:CCPxY**: PWM Least Significant bits
Capture Mode: Unused
Compare Mode: Unused
PWM Mode: These bits are the two LSbs of the PWM duty cycle. The eight MSbs are found in CCPRxL.

bit 3-0: **CCPxM3:CCPxM0**: CCPx Mode Select bits
`0000` = Capture/Compare/PWM off (resets CCPx module)
`0100` = Capture mode, every falling edge
`0101` = Capture mode, every rising edge
`0110` = Capture mode, every 4th rising edge
`0111` = Capture mode, every 16th rising edge
`1000` = Compare mode, set output on match (CCPxIF bit is set)
`1001` = Compare mode, clear output on match (CCPxIF bit is set)
`1010` = Compare mode, generate software interrupt on match (CCPxIF bit is set, CCPx pin is unaffected)
`1011` = Compare mode, trigger special event (CCPxIF bit is set; CCP1 resets TMR1; CCP2 resets TMR1 and starts an A/D conversion (if A/D module is enabled))
`11xx` = PWM mode

10.1 Capture Mode

Applicable Devices						
72	73	73A	74	74A	76	77

In Capture mode, CCPR1H:CCPR1L captures the 16-bit value of the TMR1 register when an event occurs on pin RC2/CCP1. An event is defined as:

- Every falling edge
- Every rising edge
- Every 4th rising edge
- Every 16th rising edge

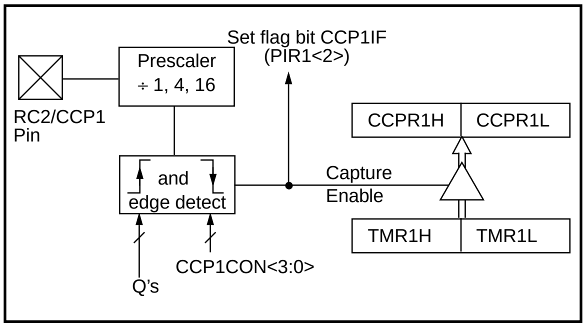
An event is selected by control bits CCP1M3:CCP1M0 (CCP1CON<3:0>). When a capture is made, the interrupt request flag bit CCP1IF (PIR1<2>) is set. It must be cleared in software. If another capture occurs before the value in register CCPR1 is read, the old captured value will be lost.

10.1.1 CCP PIN CONFIGURATION

In Capture mode, the RC2/CCP1 pin should be configured as an input by setting the TRISC<2> bit.

Note: If the RC2/CCP1 is configured as an output, a write to the port can cause a capture condition.

FIGURE 10-2: CAPTURE MODE OPERATION BLOCK DIAGRAM



10.1.2 TIMER1 MODE SELECTION

Timer1 must be running in timer mode or synchronized counter mode for the CCP module to use the capture feature. In asynchronous counter mode, the capture operation may not work.

10.1.3 SOFTWARE INTERRUPT

When the Capture mode is changed, a false capture interrupt may be generated. The user should keep bit CCP1IE (PIE1<2>) clear to avoid false interrupts and should clear the flag bit CCP1IF following any such change in operating mode.

12.2 USART Asynchronous Mode

Applicable Devices						
72	73	73A	74	74A	76	77

In this mode, the USART uses standard nonreturn-to-zero (NRZ) format (one start bit, eight or nine data bits and one stop bit). The most common data format is 8-bits. An on-chip dedicated 8-bit baud rate generator can be used to derive standard baud rate frequencies from the oscillator. The USART transmits and receives the LSb first. The USART's transmitter and receiver are functionally independent but use the same data format and baud rate. The baud rate generator produces a clock either x16 or x64 of the bit shift rate, depending on bit BRGH (TXSTA<2>). Parity is not supported by the hardware, but can be implemented in software (and stored as the ninth data bit). Asynchronous mode is stopped during SLEEP.

Asynchronous mode is selected by clearing bit SYNC (TXSTA<4>).

The USART Asynchronous module consists of the following important elements:

- Baud Rate Generator
- Sampling Circuit
- Asynchronous Transmitter
- Asynchronous Receiver

12.2.1 USART ASYNCHRONOUS TRANSMITTER

The USART transmitter block diagram is shown in Figure 12-7. The heart of the transmitter is the transmit (serial) shift register (TSR). The shift register obtains its data from the read/write transmit buffer, TXREG. The TXREG register is loaded with data in software. The TSR register is not loaded until the STOP bit has been transmitted from the previous load. As soon as the STOP bit is transmitted, the TSR is loaded with new data from the TXREG register (if available). Once the TXREG register transfers the data to the TSR register (occurs in one TCY), the TXREG register is empty and flag bit TXIF (PIR1<4>) is set. This interrupt can be enabled/disabled by setting/clearing enable bit TXIE (PIE1<4>). Flag bit TXIF will be set regardless of the state of enable bit TXIE and cannot be cleared in software. It will reset only when new data is loaded into the TXREG register. While flag bit TXIF indicated the status of the TXREG register, another bit TRMT (TXSTA<1>) shows the status of the TSR register. Status bit TRMT is a read only bit which is set when the TSR register is empty. No interrupt logic is tied to this bit, so the user has to poll this bit in order to determine if the TSR register is empty.

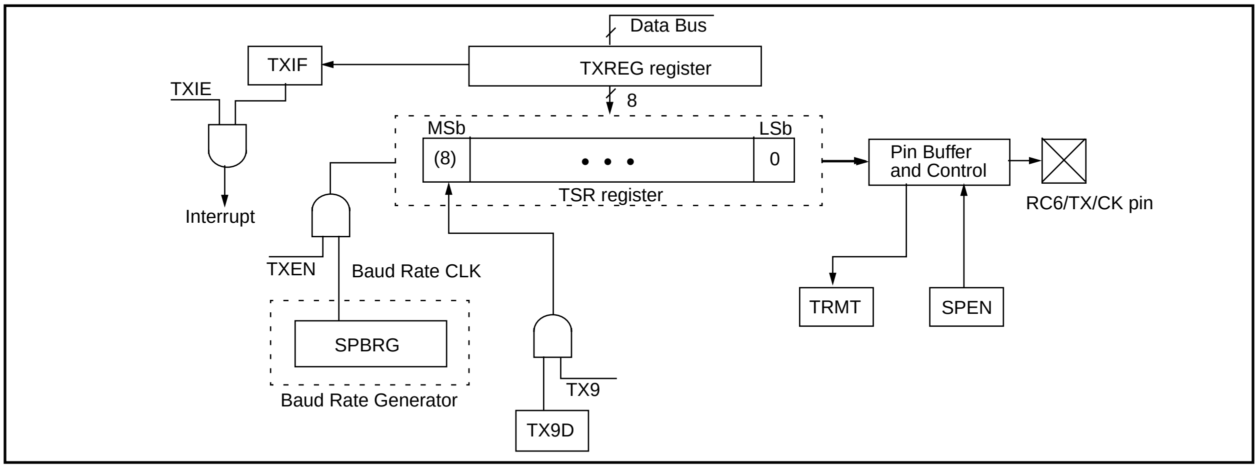
Note 1: The TSR register is not mapped in data memory so it is not available to the user.

Note 2: Flag bit TXIF is set when enable bit TXEN is set.

Transmission is enabled by setting enable bit TXEN (TXSTA<5>). The actual transmission will not occur until the TXREG register has been loaded with data and the baud rate generator (BRG) has produced a shift clock (Figure 12-7). The transmission can also be started by first loading the TXREG register and then setting enable bit TXEN. Normally when transmission is first started, the TSR register is empty, so a transfer to the TXREG register will result in an immediate transfer to TSR resulting in an empty TXREG. A back-to-back transfer is thus possible (Figure 12-9). Clearing enable bit TXEN during a transmission will cause the transmission to be aborted and will reset the transmitter. As a result the RC6/TX/CK pin will revert to hi-impedance.

In order to select 9-bit transmission, transmit bit TX9 (TXSTA<6>) should be set and the ninth bit should be written to TX9D (TXSTA<0>). The ninth bit must be written before writing the 8-bit data to the TXREG register. This is because a data write to the TXREG register can result in an immediate transfer of the data to the TSR register (if the TSR is empty). In such a case, an incorrect ninth data bit maybe loaded in the TSR register.

FIGURE 12-7: USART TRANSMIT BLOCK DIAGRAM



12.2.2 USART ASYNCHRONOUS RECEIVER

The receiver block diagram is shown in Figure 12-10. The data is received on the RC7/RX/DT pin and drives the data recovery block. The data recovery block is actually a high speed shifter operating at x16 times the baud rate, whereas the main receive serial shifter operates at the bit rate or at FOSC.

Once Asynchronous mode is selected, reception is enabled by setting bit CREN (RCSTA<4>).

The heart of the receiver is the receive (serial) shift register (RSR). After sampling the STOP bit, the received data in the RSR is transferred to the RCREG register (if it is empty). If the transfer is complete, flag bit RCIF (PIR1<5>) is set. The actual interrupt can be enabled/disabled by setting/clearing enable bit RCIE (PIE1<5>). Flag bit RCIF is a read only bit which is cleared by the hardware. It is cleared when the RCREG register has been read and is empty. The RCREG is a double buffered register, i.e. it is a two deep FIFO. It is possible for two bytes of data to be received and transferred to the RCREG FIFO and a third byte begin shifting to the RSR register. On the detection of the STOP bit of the third byte, if the RCREG register is still full then overrun error bit OERR (RCSTA<1>) will be set. The word in the RSR will be lost. The RCREG register can be read twice to retrieve the two bytes in the FIFO. Overrun bit OERR has to be cleared in software. This is done by resetting the receive logic (CREN is cleared and then set). If bit OERR is set, transfers from the RSR register to the RCREG register are inhibited, so it is essential to clear error bit OERR if it is set. Framing error bit FERR (RCSTA<2>) is set if a stop bit is detected as clear. Bit FERR and the 9th receive bit are buffered the same way as the receive data. Reading the RCREG, will load bits RX9D and FERR with new values, therefore it is essential for the user to read the RCSTA register before reading RCREG register in order not to lose the old FERR and RX9D information.

FIGURE 12-10: USART RECEIVE BLOCK DIAGRAM

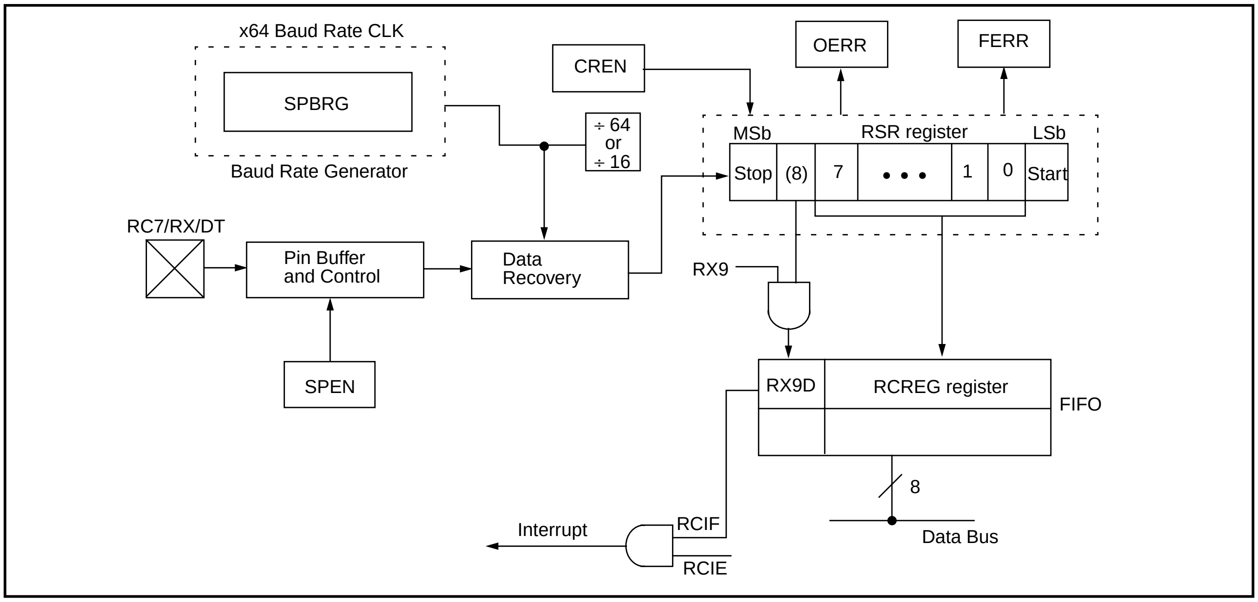
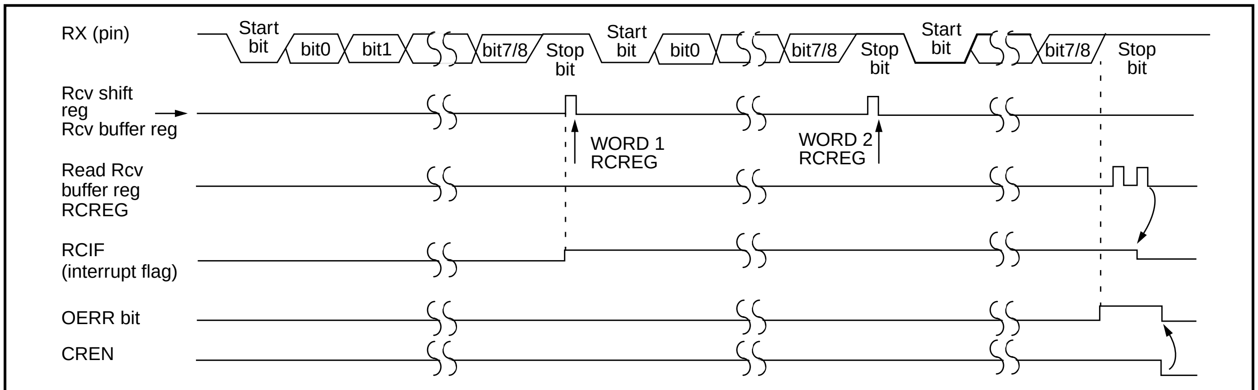


FIGURE 12-11: ASYNCHRONOUS RECEPTION



Note: This timing diagram shows three words appearing on the RX input. The RCREG (receive buffer) is read after the third word, causing the OERR (overrun) bit to be set.

Applicable Devices	72	73	73A	74	74A	76	77

17.1 DC Characteristics: PIC16C72-04 (Commercial, Industrial, Extended)
PIC16C72-10 (Commercial, Industrial, Extended)
PIC16C72-20 (Commercial, Industrial, Extended)

DC CHARACTERISTICS							**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40˚C ≤ TA ≤ +125˚C for extended, -40˚C ≤ TA ≤ +85˚C for industrial and 0˚C ≤ TA ≤ +70˚C for commercial
Param No.	**Characteristic**	**Sym**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	Supply Voltage	VDD	4.0	-	6.0	V	XT, RC and LP osc configuration
D001A			4.5	-	5.5	V	HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset Signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset Signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN bit in configuration word enabled
			3.7	4.0	4.4	V	Extended Only
D010	Supply Current (Note 2,5)	IDD	-	2.7	5.0	mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 5.5V (Note 4)
D013			-	10	20	mA	HS osc configuration FOSC = 20 MHz, VDD = 5.5V
D015	Brown-out Reset Current (Note 6)	ΔIBOR	-	350	425	µA	BOR enabled VDD = 5.0V
D020	Power-down Current (Note 3,5)	IPD	-	10.5	42	µA	VDD = 4.0V, WDT enabled, -40°C to +85°C
D021			-	1.5	16	µA	VDD = 4.0V, WDT disabled, -0°C to +70°C
D021A			-	1.5	19	µA	VDD = 4.0V, WDT disabled, -40°C to +85°C
D021B			-	2.5	19	µA	VDD = 4.0V, WDT disabled, -40°C to +125°C
D023	Brown-out Reset Current (Note 6)	ΔIBOR	-	350	425	µA	BOR enabled VDD = 5.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

Applicable Devices	72	73	73A	74	74A	76	77

17.4 Timing Parameter Symbology

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS
2. TppS
3. TCC:ST (I²C specifications only)
4. Ts (I²C specifications only)

T			
F	Frequency	T	Time

Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	$\overline{\text{RD}}$
cs	$\overline{\text{CS}}$	rw	$\overline{\text{RD}}$ or $\overline{\text{WR}}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{\text{SS}}$
dt	Data in	t0	T0CKI
io	I/O port	t1	T1CKI
mc	$\overline{\text{MCLR}}$	wr	$\overline{\text{WR}}$

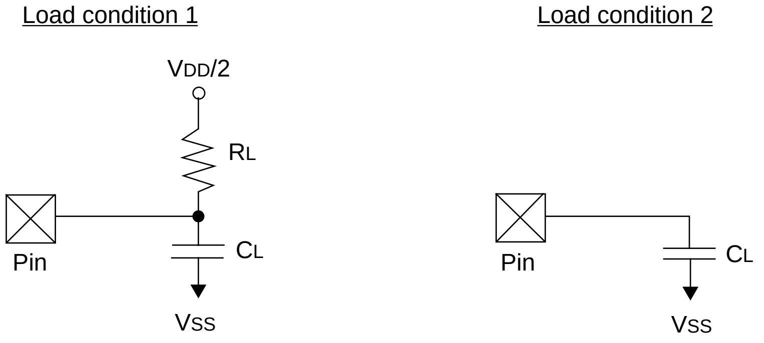
Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-impedance
I²C only			
AA	output access	High	High
BUF	Bus free	Low	Low

TCC:ST (I²C specifications only)

CC			
HD	Hold	SU	Setup
ST			
DAT	DATA input hold	STO	STOP condition
STA	START condition		

FIGURE 17-1: LOAD CONDITIONS



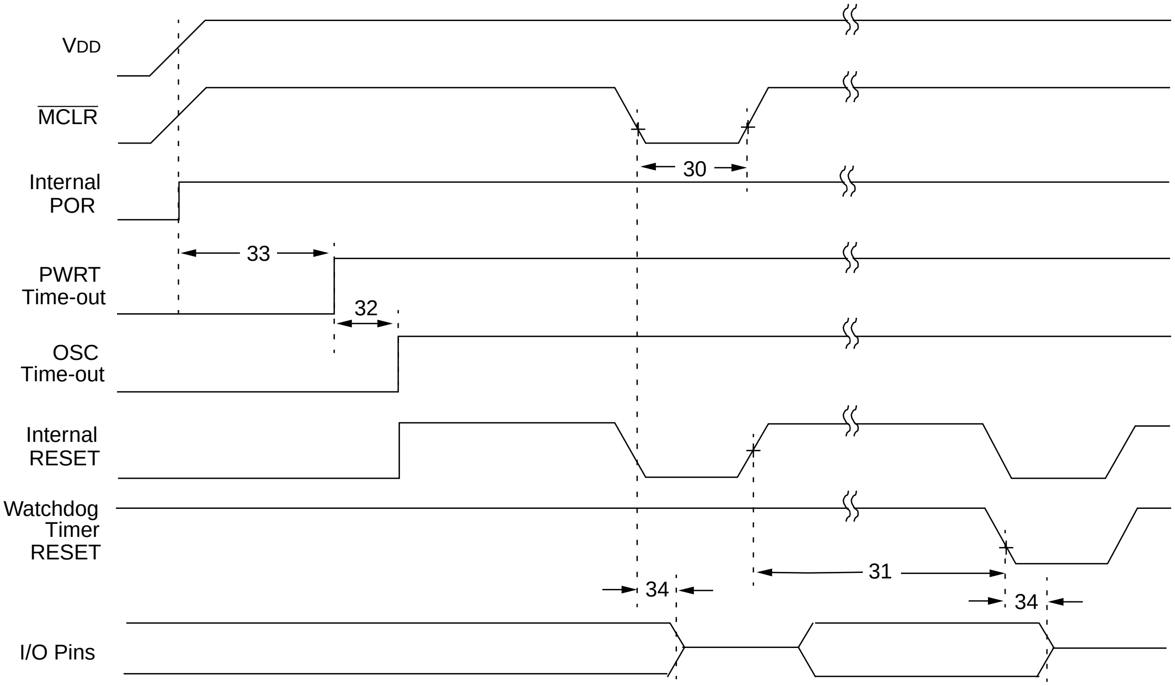
RL = 464Ω

CL = 50 pF for all pins except OSC2

15 pF for OSC2 output

Applicable Devices	72	73	73A	74	74A	76	77

FIGURE 17-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



Note: Refer to Figure 17-1 for load conditions.

FIGURE 17-5: BROWN-OUT RESET TIMING

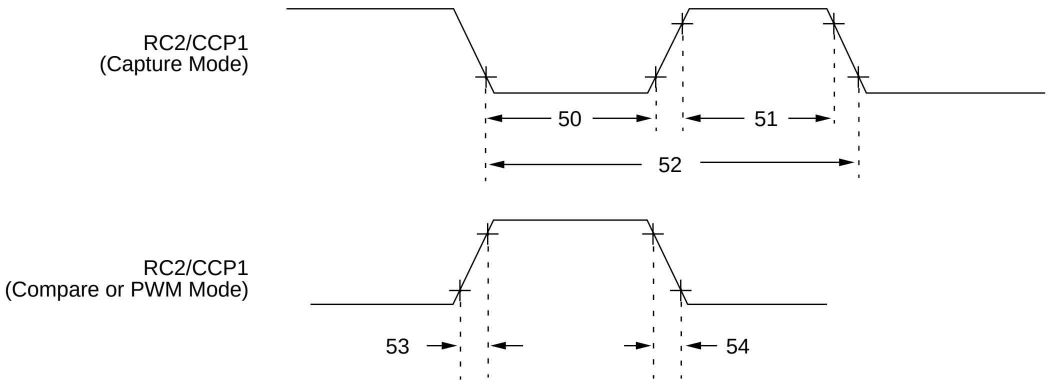
TABLE 17-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER, AND BROWN-OUT RESET REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	µs	VDD = 5V, -40˚C to +125˚C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40˚C to +125˚C
32	Tost	Oscillation Start-up Timer Period	—	1024TOSC	—	—	TOSC = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40˚C to +125˚C
34	TIOZ	I/O Hi-impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	—	—	2.1	µs	
35	TBOR	Brown-out Reset pulse width	100	—	—	µs	VDD ≤ BVDD (D005)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 17-7: CAPTURE/COMPARE/PWM TIMINGS (CCP1)



Note: Refer to Figure 17-1 for load conditions.

TABLE 17-6: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1)

Param No.	Sym	Characteristic			Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 input low time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	PIC16**C**72	10	—	—	ns	
				PIC16**LC**72	20	—	—	ns	
51*	TccH	CCP1 input high time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	PIC16**C**72	10	—	—	ns	
				PIC16**LC**72	20	—	—	ns	
52*	TccP	CCP1 input period			$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1,4 or 16)
53*	TccR	CCP1 output rise time		PIC16**C**72	—	10	25	ns	
				PIC16**LC**72	—	25	45	ns	
54*	TccF	CCP1 output fall time		PIC16**C**72	—	10	25	ns	
				PIC16**LC**72	—	25	45	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	72	73	73A	74	74A	76	77

18.3 DC Characteristics: PIC16C73/74-04 (Commercial, Industrial)
PIC16C73/74-10 (Commercial, Industrial)
PIC16C73/74-20 (Commercial, Industrial)
PIC16LC73/74-04 (Commercial, Industrial)

<table>
<tr><td colspan="2">DC CHARACTERISTICS</td><td colspan="6">Standard Operating Conditions (unless otherwise stated)
Operating temperature -40˚C ≤ TA ≤ +85˚C for industrial and
0˚C ≤ TA ≤ +70˚C for commercial
Operating voltage VDD range as described in DC spec Section 18.1 and Section 18.2.</td></tr>
<tr><th>Param No.</th><th>Characteristic</th><th>Sym</th><th>Min</th><th>Typ †</th><th>Max</th><th>Units</th><th>Conditions</th></tr>
<tr><td></td><td>Input Low Voltage</td><td></td><td></td><td></td><td></td><td></td><td></td></tr>
<tr><td></td><td>I/O ports</td><td>VIL</td><td></td><td></td><td></td><td></td><td></td></tr>
<tr><td>D030</td><td>with TTL buffer</td><td></td><td>VSS</td><td>-</td><td>0.15VDD</td><td>V</td><td>For entire VDD range</td></tr>
<tr><td>D030A</td><td></td><td></td><td>VSS</td><td>-</td><td>0.8V</td><td>V</td><td>4.5V ≤ VDD ≤ 5.5V</td></tr>
<tr><td>D031</td><td>with Schmitt Trigger buffer</td><td></td><td>VSS</td><td>-</td><td>0.2VDD</td><td>V</td><td></td></tr>
<tr><td>D032</td><td>$\overline{\text{MCLR}}$, OSC1 (in RC mode)</td><td></td><td>VSS</td><td>-</td><td>0.2VDD</td><td>V</td><td></td></tr>
<tr><td>D033</td><td>OSC1 (in XT, HS and LP)</td><td></td><td>VSS</td><td>-</td><td>0.3VDD</td><td>V</td><td>Note1</td></tr>
<tr><td></td><td>Input High Voltage</td><td></td><td></td><td></td><td></td><td></td><td></td></tr>
<tr><td></td><td>I/O ports</td><td>VIH</td><td></td><td>-</td><td></td><td></td><td></td></tr>
<tr><td>D040</td><td>with TTL buffer</td><td></td><td>2.0</td><td>-</td><td>VDD</td><td>V</td><td>4.5V ≤ VDD ≤ 5.5V</td></tr>
<tr><td>D040A</td><td></td><td></td><td>0.25VDD + 0.8V</td><td>-</td><td>VDD</td><td>V</td><td>For entire VDD range</td></tr>
<tr><td>D041</td><td>with Schmitt Trigger buffer</td><td></td><td>0.8VDD</td><td>-</td><td>VDD</td><td>V</td><td>For entire VDD range</td></tr>
<tr><td>D042</td><td>$\overline{\text{MCLR}}$</td><td></td><td>0.8VDD</td><td>-</td><td>VDD</td><td>V</td><td></td></tr>
<tr><td>D042A</td><td>OSC1 (XT, HS and LP)</td><td></td><td>0.7VDD</td><td>-</td><td>VDD</td><td>V</td><td>Note1</td></tr>
<tr><td>D043</td><td>OSC1 (in RC mode)</td><td></td><td>0.9VDD</td><td>-</td><td>VDD</td><td>V</td><td></td></tr>
<tr><td>D070</td><td>PORTB weak pull-up current</td><td>IPURB</td><td>50</td><td>250</td><td>400</td><td>μA</td><td>VDD = 5V, VPIN = VSS</td></tr>
<tr><td></td><td>Input Leakage Current
(Notes 2, 3)</td><td></td><td></td><td></td><td></td><td></td><td></td></tr>
<tr><td>D060</td><td>I/O ports</td><td>IIL</td><td>-</td><td>-</td><td>±1</td><td>μA</td><td>Vss ≤ VPIN ≤ VDD, Pin at hi-impedance</td></tr>
<tr><td>D061</td><td>$\overline{\text{MCLR}}$, RA4/T0CKI</td><td></td><td>-</td><td>-</td><td>±5</td><td>μA</td><td>Vss ≤ VPIN ≤ VDD</td></tr>
<tr><td>D063</td><td>OSC1</td><td></td><td>-</td><td>-</td><td>±5</td><td>μA</td><td>Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration</td></tr>
<tr><td></td><td>Output Low Voltage</td><td></td><td></td><td></td><td></td><td></td><td></td></tr>
<tr><td>D080</td><td>I/O ports</td><td>VOL</td><td>-</td><td>-</td><td>0.6</td><td>V</td><td>IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C</td></tr>
<tr><td>D083</td><td>OSC2/CLKOUT (RC osc config)</td><td></td><td>-</td><td>-</td><td>0.6</td><td>V</td><td>IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C</td></tr>
<tr><td></td><td>Output High Voltage</td><td></td><td></td><td></td><td></td><td></td><td></td></tr>
<tr><td>D090</td><td>I/O ports (Note 3)</td><td>VOH</td><td>VDD - 0.7</td><td>-</td><td>-</td><td>V</td><td>IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C</td></tr>
<tr><td>D092</td><td>OSC2/CLKOUT (RC osc config)</td><td></td><td>VDD - 0.7</td><td>-</td><td>-</td><td>V</td><td>IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C</td></tr>
<tr><td>D150*</td><td>Open-Drain High Voltage</td><td>VOD</td><td>-</td><td>-</td><td>14</td><td>V</td><td>RA4 pin</td></tr>
</table>

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C7X be driven with external clock in RC mode.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

Applicable Devices	72	73	73A	74	74A	76	77

19.1 DC Characteristics: PIC16C73A/74A-04 (Commercial, Industrial, Extended)
PIC16C73A/74A-10 (Commercial, Industrial, Extended)
PIC16C73A/74A-20 (Commercial, Industrial, Extended)

DC CHARACTERISTICS

Standard Operating Conditions (unless otherwise stated)
Operating temperature -40˚C ≤ TA ≤ +125˚C for extended,
-40˚C ≤ TA ≤ +85˚C for industrial and
0˚C ≤ TA ≤ +70˚C for commercial

Param No.	Characteristic	Sym	Min	Typ†	Max	Units	Conditions
D001	Supply Voltage	VDD	4.0	-	6.0	V	XT, RC and LP osc configuration
D001A			4.5	-	5.5	V	HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN bit in configuration word enabled
			3.7	4.0	4.4	V	Extended Range Only
D010	Supply Current (Note 2,5)	IDD	-	2.7	5	mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 5.5V (Note 4)
D013			-	10	20	mA	HS osc configuration FOSC = 20 MHz, VDD = 5.5V
D015*	Brown-out Reset Current (Note 6)	ΔIBOR	-	350	425	µA	BOR enabled VDD = 5.0V
D020	Power-down Current (Note 3,5)	IPD	-	10.5	42	µA	VDD = 4.0V, WDT enabled, -40°C to +85°C
D021			-	1.5	16	µA	VDD = 4.0V, WDT disabled, -0°C to +70°C
D021A			-	1.5	19	µA	VDD = 4.0V, WDT disabled, -40°C to +85°C
D021B			-	2.5	19	µA	VDD = 4.0V, WDT disabled, -40°C to +125°C
D023*	Brown-out Reset Current (Note 6)	ΔIBOR	-	350	425	µA	BOR enabled VDD = 5.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

Applicable Devices	72	73	73A	74	74A	76	77

19.4 Timing Parameter Symbology

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS
2. TppS
3. TCC:ST (I^{2}C specifications only)
4. Ts (I^{2}C specifications only)

T			
F	Frequency	T	Time

Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	$\overline{\text{RD}}$
cs	$\overline{\text{CS}}$	rw	$\overline{\text{RD}}$ or $\overline{\text{WR}}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{\text{SS}}$
dt	Data in	t0	T0CKI
io	I/O port	t1	T1CKI
mc	$\overline{\text{MCLR}}$	wr	$\overline{\text{WR}}$

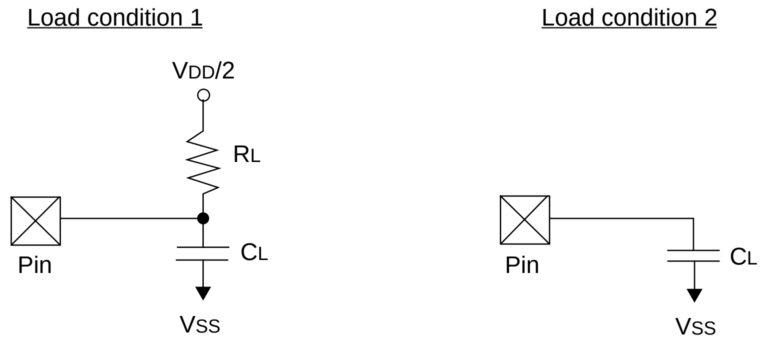
Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-impedance
I^{2}C only			
AA	output access	High	High
BUF	Bus free	Low	Low

TCC:ST (I^{2}C specifications only)

CC			
HD	Hold	SU	Setup
ST			
DAT	DATA input hold	STO	STOP condition
STA	START condition		

FIGURE 19-1: LOAD CONDITIONS



RL = 464Ω

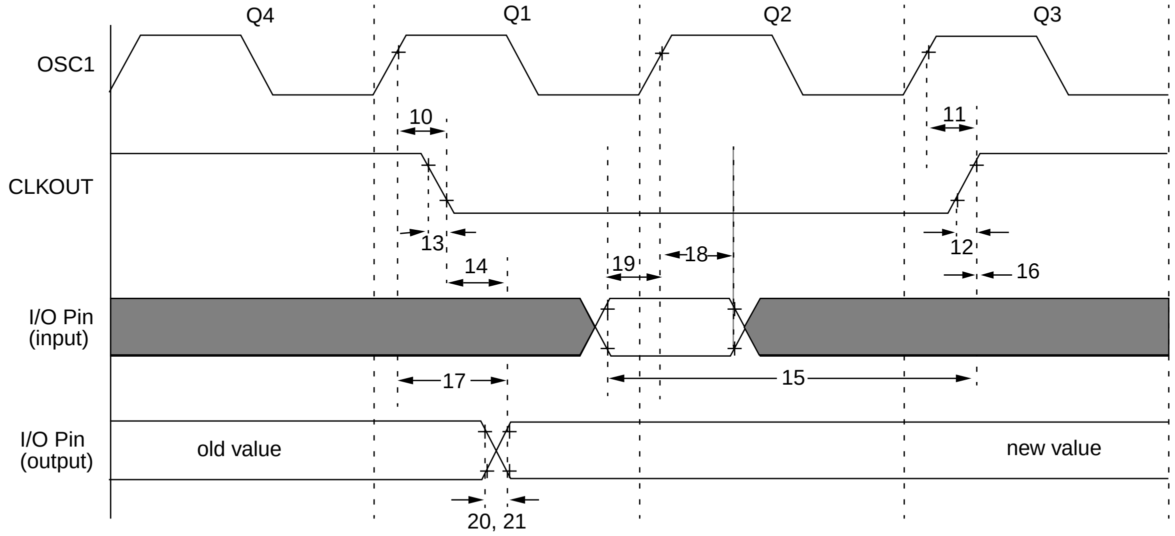
CL = 50 pF for all pins except OSC2, but including PORTD and PORTE outputs as ports

15 pF for OSC2 output

Note: PORTD and PORTE are not implemented on the PIC16C73A.

Applicable Devices	72	73	73A	74	74A	76	77

FIGURE 19-3: CLKOUT AND I/O TIMING



Note: Refer to Figure 19-1 for load conditions.

TABLE 19-3: CLKOUT AND I/O TIMING REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓		—	75	200	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑		—	75	200	ns	Note 1
12*	TckR	CLKOUT rise time		—	35	100	ns	Note 1
13*	TckF	CLKOUT fall time		—	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT ↓ to Port out valid		—	—	0.5TCY + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT ↑		TOSC + 200	—	—	ns	Note 1
16*	TckH2ioI	Port in hold after CLKOUT ↑		0	—	—	ns	Note 1
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid		—	50	150	ns	
18*	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	PIC16**C**73A/74A	100	—	—	ns	
			PIC16**LC**73A/74A	200	—	—	ns	
19*	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)		0	—	—	ns	
20*	TioR	Port output rise time	PIC16**C**73A/74A	—	10	40	ns	
			PIC16**LC**73A/74A	—	—	80	ns	
21*	TioF	Port output fall time	PIC16**C**73A/74A	—	10	40	ns	
			PIC16**LC**73A/74A	—	—	80	ns	
22††*	Tinp	INT pin high or low time		TCY	—	—	ns	
23††*	Trbp	RB7:RB4 change INT high or low time		TCY	—	—	ns	

* These parameters are characterized but not tested.

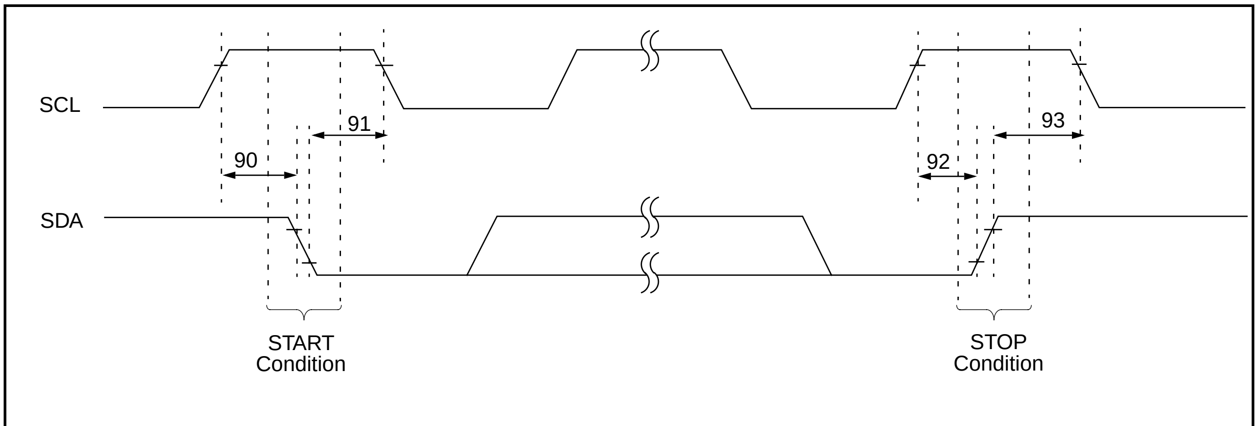
†Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

†† These parameters are asynchronous events not related to any internal clock edges.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x TOSC.

Applicable Devices	72	73	73A	74	74A	76	77

FIGURE 19-10: I^{2}C BUS START/STOP BITS TIMING



Note: Refer to Figure 19-1 for load conditions

TABLE 19-9: I^{2}C BUS START/STOP BITS REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ	Max	Units	Conditions
90	TSU:STA	START condition	100 kHz mode	4700	—	—	ns	Only relevant for repeated START condition
		Setup time	400 kHz mode	600	—	—		
91	THD:STA	START condition	100 kHz mode	4000	—	—	ns	After this period the first clock pulse is generated
		Hold time	400 kHz mode	600	—	—		
92	TSU:STO	STOP condition	100 kHz mode	4700	—	—	ns	
		Setup time	400 kHz mode	600	—	—		
93	THD:STO	STOP condition	100 kHz mode	4000	—	—	ns	
		Hold time	400 kHz mode	600	—	—		

Applicable Devices	72	73	73A	74	74A	76	77

DC CHARACTERISTICS	Standard Operating Conditions (unless otherwise stated) Operating temperature -40˚C ≤ T_A ≤ +125˚C for extended, -40˚C ≤ T_A ≤ +85˚C for industrial and 0˚C ≤ T_A ≤ +70˚C for commercial Operating voltage V_{DD} range as described in DC spec Section 20.1 and Section 20.2.

Param No.	Characteristic	Sym	Min	Typ †	Max	Units	Conditions
	Output High Voltage						
D090	I/O ports (Note 3)	V_{OH}	V_{DD} - 0.7	-	-	V	I_{OH} = -3.0 mA, V_{DD} = 4.5V, -40°C to +85°C
D090A			V_{DD} - 0.7	-	-	V	I_{OH} = -2.5 mA, V_{DD} = 4.5V, -40°C to +125°C
D092	OSC2/CLKOUT (RC osc config)		V_{DD} - 0.7	-	-	V	I_{OH} = -1.3 mA, V_{DD} = 4.5V, -40°C to +85°C
D092A			V_{DD} - 0.7	-	-	V	I_{OH} = -1.0 mA, V_{DD} = 4.5V, -40°C to +125°C
D150*	**Open-Drain High Voltage**	V_{OD}	-	-	14	V	RA4 pin
	Capacitive Loading Specs on Output Pins						
D100	OSC2 pin	C_{OSC2}	-	-	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101	All I/O pins and OSC2 (in RC mode)	C_{IO}	-	-	50	pF	
D102	SCL, SDA in I^2C mode	C_B	-	-	400	pF	

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

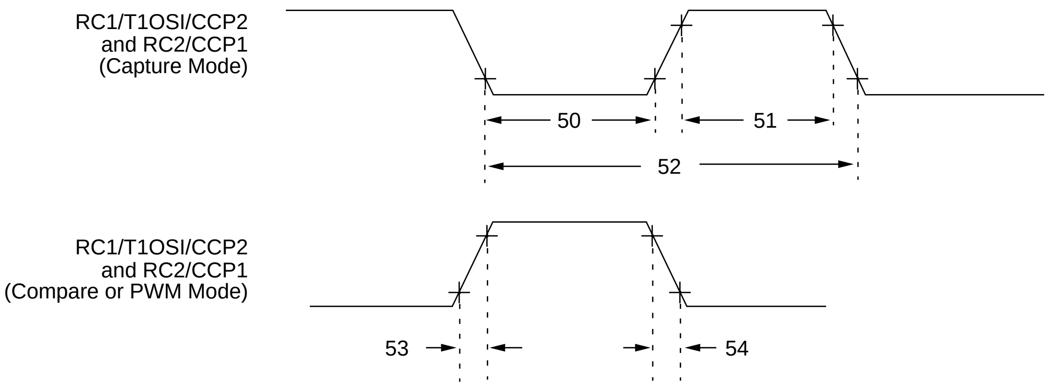
Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C7X be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

Applicable Devices	72	73	73A	74	74A	76	77

FIGURE 20-7: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)



Note: Refer to Figure 20-1 for load conditions.

TABLE 20-6: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1 AND CCP2)

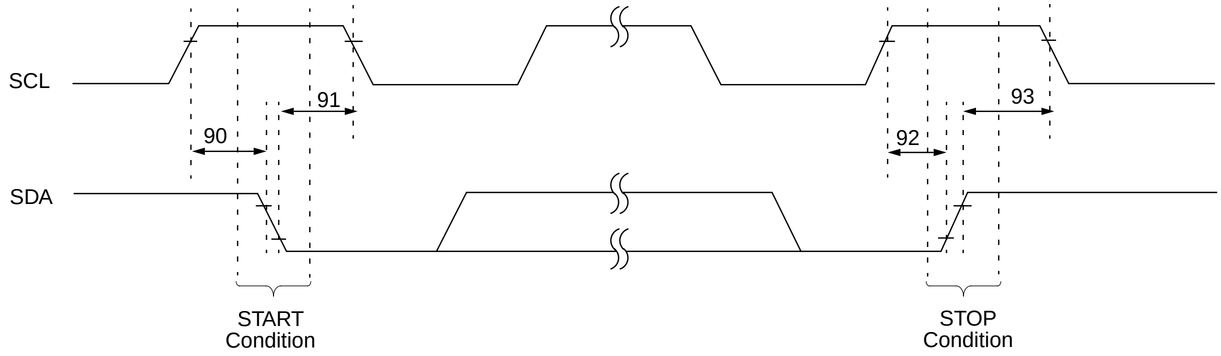
Param No.	Sym	Characteristic			Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 and CCP2 input low time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	PIC16**C**76/77	10	—	—	ns	
				PIC16**LC**76/77	20	—	—	ns	
51*	TccH	CCP1 and CCP2 input high time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	PIC16**C**76/77	10	—	—	ns	
				PIC16**LC**76/77	20	—	—	ns	
52*	TccP	CCP1 and CCP2 input period			$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1,4 or 16)
53*	TccR	CCP1 and CCP2 output rise time		PIC16**C**76/77	—	10	25	ns	
				PIC16**LC**76/77	—	25	45	ns	
54*	TccF	CCP1 and CCP2 output fall time		PIC16**C**76/77	—	10	25	ns	
				PIC16**LC**76/77	—	25	45	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated.
These parameters are for design guidance only and are not tested.

Applicable Devices	72	73	73A	74	74A	76	77

FIGURE 20-13: I²C BUS START/STOP BITS TIMING

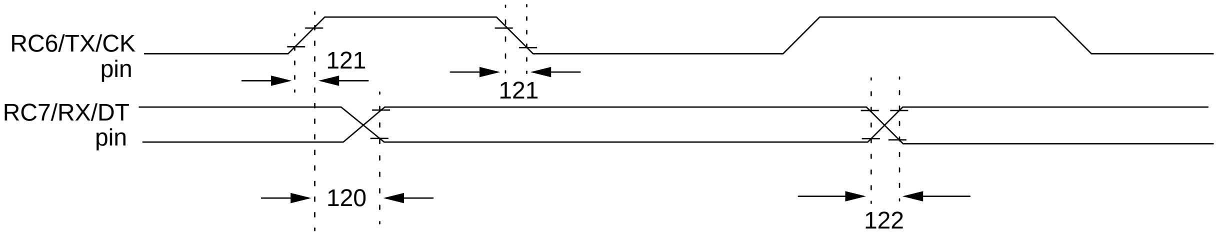


Note: Refer to Figure 20-1 for load conditions

TABLE 20-9: I²C BUS START/STOP BITS REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ	Max	Units	Conditions
90	TSU:STA	START condition	100 kHz mode	4700	—	—	ns	Only relevant for repeated START condition
		Setup time	400 kHz mode	600	—	—		
91	THD:STA	START condition	100 kHz mode	4000	—	—	ns	After this period the first clock pulse is generated
		Hold time	400 kHz mode	600	—	—		
92	TSU:STO	STOP condition	100 kHz mode	4700	—	—	ns	
		Setup time	400 kHz mode	600	—	—		
93	THD:STO	STOP condition	100 kHz mode	4000	—	—	ns	
		Hold time	400 kHz mode	600	—	—		

FIGURE 20-15: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING



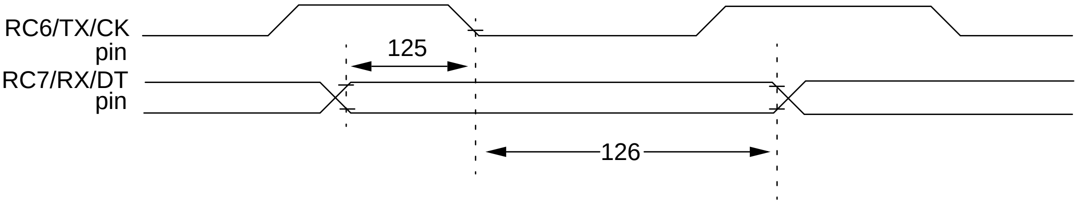
Note: Refer to Figure 20-1 for load conditions

TABLE 20-11: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
120	TckH2dtV	SYNC XMIT (MASTER & SLAVE) Clock high to data out valid	PIC16**C**76/77	—	—	80	ns	
			PIC16**LC**76/77	—	—	100	ns	
121	Tckrf	Clock out rise time and fall time (Master Mode)	PIC16**C**76/77	—	—	45	ns	
			PIC16**LC**76/77	—	—	50	ns	
122	Tdtrf	Data out rise time and fall time	PIC16**C**76/77	—	—	45	ns	
			PIC16**LC**76/77	—	—	50	ns	

†: Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 20-16: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



Note: Refer to Figure 20-1 for load conditions

TABLE 20-12: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
125	TdtV2ckL	SYNC RCV (MASTER & SLAVE) Data setup before CK ↓ (DT setup time)	15	—	—	ns	
126	TckL2dtl	Data hold after CK ↓ (DT hold time)	15	—	—	ns	

†: Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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